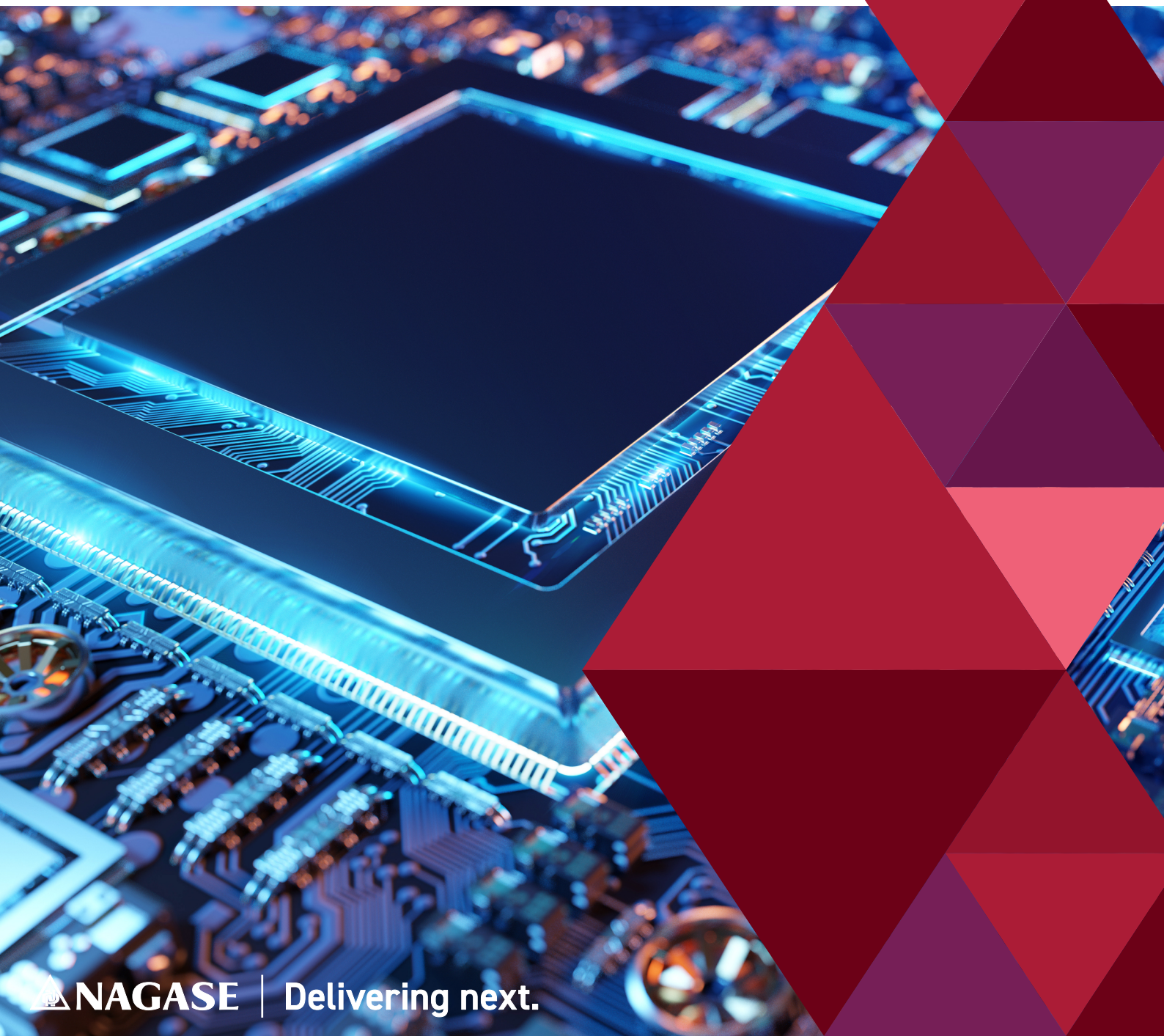




Material for Power Device and Electronic Components

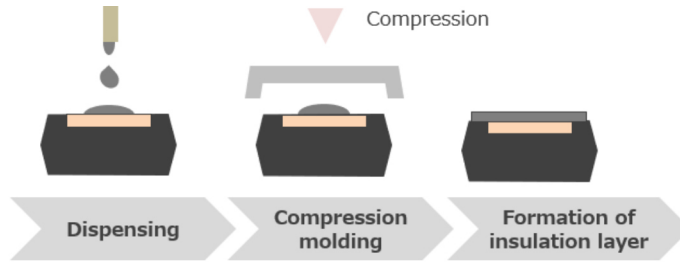
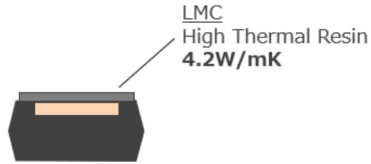
Molding Compound



Rigid Thermal-Conductive Layer by Mold Process

High Thermal Liquid Molding Compound

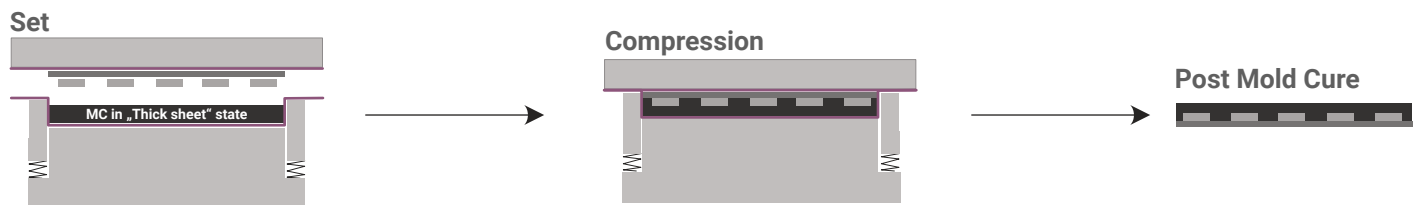
Power device, E-Component



Item	Unit	T-700/R-5601
Feature	-	High Thermal Conductivity
Filler Content	wt %	91
Filler Top Cut	µm	90
Filler Average Size	µm	47
Specific Gravity	-	3.12
Viscosity (25 °C)	Pa*s	1000
Flexural Modulus (25 °C)	GPa	30
Tg (DMA)	°C	70
CTE1	x 10 ⁻⁶ /K	12
CTE2	x 10 ⁻⁶ /K	44
Thermal Conductivity (Xe Flash Method)	W/mk	4.2
IMC Condition	-	150 °C / 3 min
PMC Condition	-	150 °C / 1 h

Thick Layer Encapsulation by Compression Molding

New Molding Compound Concept



Feature	Condition	Advantage
Method	Compression Molding	• No scrapping of mold due to no runner
Material Type	„Thick sheet“ e.g. 1 - 3 mm thickness	• Good UPH (no need of dispensing) • Large area molding
Low Temperature	IMC condition: 125 °C / 10 min	-
Low Pressure	< 3 - 5 MPa	• Low stress & good filling
Additional Function	e.g. Thermal conductivity (> 3.0 W / mK)	-

